12500 TI Boulevard, MS 8640, Dallas, Texas 75243

Notification# 20200715000
Datasheet for LMV321, LMV324, LMV358
Information Only

Date: July 21, 2020
To: TOKYO ELECTRON DEVICE (DSTR) PCN

Dear Customer:

This is an information-only announcement of a change to the datasheet for a device that is currently offered by Texas Instruments.

The changes discussed within this notification are for your information only.

Any negotiated alternative change requirements will be provided via the customer's defined process. Customers with previously negotiated, special requirements will be handled separately. Any inquiries should be directed to your local Field Sales Representative.

For questions regarding this notice, contact your local Field Sales Representative or the PCN team (PCN_ww_admin_team@list.ti.com).

Sincerely,

PCN Team
SC Business Services

Information Only
Attachments

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
LMV358IDDUR	null
LMV321IDBVT	null
LMV321IDCKT	null
LMV324IDR	null
LMV324IPWR	null
LMV358IDGKR	null
LMV358IDR	null
LMV358IPWR	null
LMV358ID	null
LMV321IDBVR	null
LMV321IDCKR	null
LMV324IPWRG4	null
LMV321IDCKRG4	null
LMV358IDRG4	null
LMV324QPWR	null
LMV358QDGKR	null

Technical details of this Product Change follow on the next page(s).

Notification Number:	20200715000	Notification Date:	July 21, 2020
Title:	Datasheet for LMV321, LMV324, LMV358		
Customer Contact:	PCN Manager	Dept:	Quality Services

Change Type:					
☐	Assembly Site	☐	Design	☐	Wafer Bump Site
☐	Assembly Process	☒	Data Sheet	☐	Wafer Bump Material
☐	Assembly Materials	☐	Part number change	☐	Wafer Bump Process
☐	Mechanical Specification	☐	Test Site	☐	Wafer Fab Site
☐	Packing/Shipping/Labeling	☐	Test Process	☐	Wafer Fab Materials
				☐	Wafer Fab Process

Notification Details

Description of Change:

Texas Instruments Incorporated is announcing an information only notification.
The product datasheet(s) is being updated as summarized below.
The following change history provides further details.

TEXAS INSTRUMENTS

LMV321, LMV324, LMV358

SLOS263X – AUGUST 1999 – REVISED MAY 2020

Changes from Revision W (October 2014) to Revision X	Page
• Deleted LMV324S mentions on the front page of the data sheet	1
• Added end equipment links in *Application* section	1
• Added recommended device notice for LMV321A, LMV358A, and LMV324A	1
• Changed *Device Information* table to sort devices by channel count in ascending order	1
• Changed *Pin Configuration and Functions* section by dividing the Pin Functions table into separate tables per device	3
• Deleted LMV324S pinout information	4
• Changed HBM ESD voltage from 2500 V to 2000 V	5
• Changed CDM ESD voltage from 1500 V to 1000 V	5
• Deleted Shutdown voltage threshold for LMV324S	5
• Changed *Thermal Information* section by dividing the *Thermal Information* table into separate tables per device	5
• Changed Thermal Information for LMV321	5
• Deleted LMV324S Thermal Information	5
• Changed Thermal Information for LMV324	5
• Changed Thermal Information for LMV358	6
• Deleted LMV324S test condition for supply current	7
• Changed output short-circuit current for sourcing from 60 mA to 40 mA	8
• Changed output short-circuit current for sinking from 160 mA to 40 mA	8
• Deleted LMV324S test condition for supply current	8
• Added assured by characterization table notes to output short-circuit current, output swing, and input bias current specifications	8
• Changed Source Current Vs Output Voltage V_{CC}=2.7V plot with Output Voltage vs Output Current (Claw) plot in *Typical Characteristics* section	10
• Deleted plots Source Current Vs Output Voltage V_{CC}= 5V, Sinking Current vs Output Voltage V_{CC}=2.7V, Sinking Current vs Output Voltage V_{CC}=5V, Short-Circuit Current vs Temperature in *Typical Characteristics* section	10
• Changed Open-Loop Output Impedance Vs Frequency plot in *Typical Characteristics* section	12
• Added *Receiving Notification* and *Support Resources* sections to the *Device and Documentation Support* section	23

The datasheet number will be changing.

Device Family	Change From:	Change To:
LMV321, LMV324, LMV358	SLOS263W	SLOS263X

These changes may be reviewed at the datasheet links provided.

http://www.ti.com/product/LMV321

Reason for Change:

To accurately reflect device characteristics.

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

No anticipated impact. This is a specification change announcement only. There are no changes to the actual device.

Changes to product identification resulting from this notification:

None.

Product Affected:

LMV321IDBVR	LMV321IDBVRE4	LMV321IDBVRG4	LMV321IDBVT
LMV321IDBVTE4	LMV321IDCKR	LMV321IDCKRG4	LMV321IDCKT
LMV324ID	LMV324IDR	LMV324IDRE4	LMV324IDRG4
LMV324IPWR	LMV324IPWRE4	LMV324IPWRG4	LMV324QD
LMV324QDG4	LMV324QDR	LMV324QDRG4	LMV324QPW
LMV324QPWR	LMV324QPWRE4	LMV358ID	LMV358IDDUR
LMV358IDDURG4	LMV358IDG4	LMV358IDGKR	LMV358IDGKRG4
LMV358IDR	LMV358IDRE4	LMV358IPWG4	LMV358IDRG4
LMV358IPW	LMV358IPWR	LMV358IPWRE4	LMV358IPWRG4
LMV358QD	LMV358QDDUR	LMV358QDDURG4	LMV358QDG4
LMV358QDGKR	LMV358QDGKRG4	LMV358QDR	LMV358QPWR

For questions regarding this notice, e-mails can be sent to the contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
WW PCN Team	PCN_ww_admin_team@list.ti.com

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